



AMENDMENTS

Please cancel claims 18-21 without prejudice or disclaimer.

Please substitute the following claims 1, 3, 11, 12 and 15 for claims of the same number previously pending.

1. (Twice Amended) A printed circuit board comprising:

a printed wiring board;  
a plurality of components mounted on said printed wiring board, wherein the printed circuit board has a cavity with one or more openings to the surface of the printed circuit board; and  
an electrically non-conductive filler material disposed in the cavity and on the surface of the printed circuit board immediately surrounding the cavity so as to bridge across and at least partially infill the one or more openings of the cavity, wherein the filler material renders the cavity substantially inaccessible to subsequently-applied coatings.

3. (Twice Amended) The printed circuit board of claim 1, wherein the cavity comprises:

a volume of space defined by leads of a component, the component body and said printed wiring board, wherein the volume of space has a plurality of openings to the surface of the printed circuit board between neighboring component leads.

11. (Twice Amended) The printed circuit board of claim 1, wherein the subsequently-applied coating comprises:

a layer of dielectric coating that conformingly coats exposed surfaces of the printed circuit board including the filler material, the dielectric coating formed of a low viscosity material that facilitates accurate application of the dielectric coating using a spray atomized technique, wherein the at least one of the cavity openings is sufficiently large to prevent the dielectric coating from bridging across the cavity opening without the presence of the filler material.

12. (Twice Amended) A printed circuit board comprising:

a printed wiring board;

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a plurality of components having a device body mounted on said printed wiring board to form one or more regions of the printed circuit board having a highly variable and cavitational surface including a plurality of cavities defined by component leads, the component body adjacent the series of leads, and a portion of the printed wiring board below the series of leads, wherein each cavity includes a plurality of openings to the surface of the printed circuit board; and

a layer of non-electrically-conductive filler material conformingly adhered to printed circuit board surfaces in the one or more regions to provide a contoured, contiguous filler material surface having gradual transitions, wherein the filler material bridges across the cavity openings and at least partially infills the cavities.

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15. (Twice Amended) The printed circuit board of claim 14, further comprising:

a low viscosity, high adherence dielectric coating that, when applied and cured, covers predetermined portions of said printed circuit board including at least a portion of the one or more regions coated with said filler material, wherein the filler material prevents the dielectric coating from entering the plurality of cavities.

#### REMARKS

1. In response to the Office Action mailed August 28, 2002, Applicants respectfully request reconsideration. Claims 1 and 3-21 were last presented for examination. Claims 1 and 3-17 were rejected in the outstanding Office Action. Non-elected claims 18-21 were withdrawn from consideration by the Examiner. By the foregoing amendments, claims 1 3, 11, 12 and 15 have been amended. Claims 18-21 have been canceled without prejudice or disclaimer. No claims have been added. Thus, upon entry of this paper, claims 1 and 3-17 will be pending in this application.

2. These amendments are not intended to narrow the scope of the claims in any way. Further, these amendments are believed not to introduce new matter and the entry is respectfully requested. Based upon the following Remarks only, Applicants respectfully requests that all outstanding objections and rejections be reconsidered, and that they be withdrawn.